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SE30ND, SE30NG, SE30NJ

Vishay General Semiconductor

Surface-Mount Standard Rectifier



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS								
I _{F(AV)} 3 A								
V _{RRM}	200 V, 400 V, 600 V							
I _{FSM}	40 A							
V _F at I _F = 3 A (T _J = 125 °C)	0.86 V							
T _J max.	175 °C							
Package	DFN3820A							
Circuit configuration	Single							

FEATURES

- Low-profile package- typical height of 0.88 mm
- Leadless DFN package with side-wettable flanks suitable for customer AOI (Automatic Optical Inspection)
- Ideal for automated replacement
- Oxide planar chip junction
- Low forward voltage drop
- Typical IR less than 0.1 µA
- ESD capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available - Automotive ordering code: base P/NHM3
- Compatible to SMP (DO-220AA) package case outline
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

General purpose, power line polarity protection and rail-to-rail protection in consumer, industrial, and automotive applications.

MECHANICAL DATA

Case: DFN3820A

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test **Polarity:** color band denotes cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)								
PARAMETER	SYMBOL	SE30ND	SE30NG	SE30NJ	UNIT			
Device marking code		3D	3G	3J				
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	V			
Maximum average forward rectified current (fig.1)	I _{F(AV)} ⁽¹⁾		А					
Maximum average forward rectilied current (lig. r)	I _{F(AV)} ⁽²⁾							
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM}		А					
Operating junction temperature range	T _J ⁽³⁾		°C					
Storage temperature range	T _{STG}							

Notes

⁽¹⁾ Mounted on 20 x 20mm pad area, 2 oz. FR4 PCB

⁽²⁾ Free air, mounted on recommended copper pad area

 $^{(3)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

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RoHS

COMPLIANT HALOGEN

FREE



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ELECTRICAL CHARACTERISTICS ($T_J = 25 \text{ °C}$ unless otherwise noted)								
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT		
	I _F = 1.5 A	T _{.1} = 25 °C	V _F ⁽¹⁾	0.91	-	V		
Instantaneous forward voltage	I _F = 3 A	1 _J = 25 C		0.97	1.1			
	I _F = 1.5 A	T _J = 125 °C		0.79	-			
	I _F = 3 A			0.86	0.98			
Reverse current	Rated V _B	T _J = 25 °C	I _R ⁽²⁾	-	10	μA		
	naleu v _R	T _J = 125 °C		13	100			
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 01 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}	1500	-	ns		
Typical junction capacitance	4.0 V, 1 MHz		CJ	19	-	pF		

Notes

 $^{(1)}\,$ Pulse test: 300 μs pulse width, 1 % duty cycle

⁽²⁾ Pulse test: pulse width \leq 5 ms

THERMAL CHARACTERISTICS ($T_A = 25 \text{ °C}$ unless otherwise specified)								
PARAMETER SYMBOL TYP. MAX. UNIT								
Thermal resistance	R _{0JA} (1)(2)	135	169	°C/W				
	R _{θJM} ⁽³⁾	5	6.3	C/W				

Notes

⁽¹⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

⁽³⁾ Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS

(T _A = 25 $^{\circ}$ C unless otherwise noted)								
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE			
AEC-Q101-001	Human body model (contact mode)	C = 100 pF, R = 1.5 k Ω		H3B	> 8 kV			
AEC-Q101-002	Machine model (contact mode)	C = 200 pF, R = 0 Ω		M4	> 400 V			
JESD22-A114	Human body model (contact mode)	C = 100 pF, R = 1.5 k Ω	V	3B	> 8 kV			
JESD22-A115	Machine model (contact mode)	C = 200 pF, R = 0 Ω	V _C	С	> 400 V			
IEC 61000-4-2 ⁽²⁾	Human body model (contact mode)	C = 150 pF, R = 330 Ω		4	> 8 kV			
	Human body model (air-discharge mode) ⁽¹⁾	C = 150 pF, R = 330 Ω		4	> 15 kV			

Notes

⁽¹⁾ Immunity to IEC 61000-4-2 air discharge mode has a typical performance > 30 kV

(2) System ESD standard



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ORDERING INFORMATION TABLE

			r	r	r	r	r
Device code	S	E	30	N	J	н	М3
	1	2	3	4	5	6	7
	1	- Vis	hay star	ndard re	covery p	oroduct	
	2	- Oxi	de plana	ar chip t	echnolog	gу	
	3	- Cur	rent rati	ng (30 =	= 3 A)		
	4	- Pac	ckage ty	pe (N =	DFN pa	ckage)	
	5	- Vol	tage rati	ing (D =	200 V, (G = 400	V, J = 6
	6	- Qua	ality gra	de (H =	AEC-Q1	01 qual	ified, ot
	7				ient cate nd termi	•••	

ORDERING INFORMATION (Example)								
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE				
SE30NJ-M3/H	0.023	Н	3500	7" diameter plastic tape and reel				
SE30NJ-M3/I	0.023	I	14 000	13" diameter plastic tape and reel				
SE30NJHM3/H ⁽¹⁾	0.023	Н	3500	7" diameter plastic tape and reel				
SE30NJHM3/I ⁽¹⁾	0.023	Ι	14 000	13" diameter plastic tape and reel				

Note

⁽¹⁾ AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

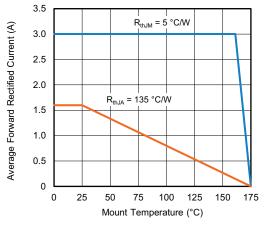


Fig. 1 - Maximum Forward Current Derating Curve

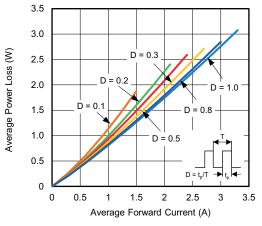


Fig. 2 - Forward Power Loss Characteristics

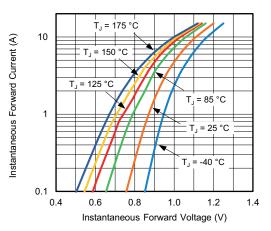


Fig. 3 - Typical Instantaneous Forward Characteristics

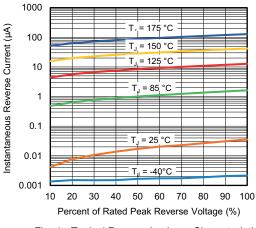


Fig. 4 - Typical Reverse Leakage Characteristics

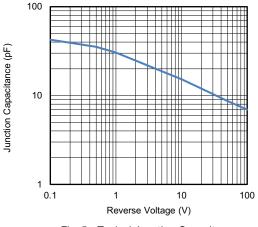


Fig. 5 - Typical Junction Capacitance

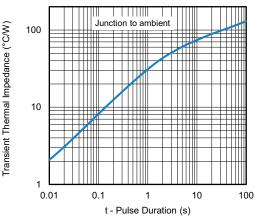


Fig. 6 - Typical Transient Thermal Impedance

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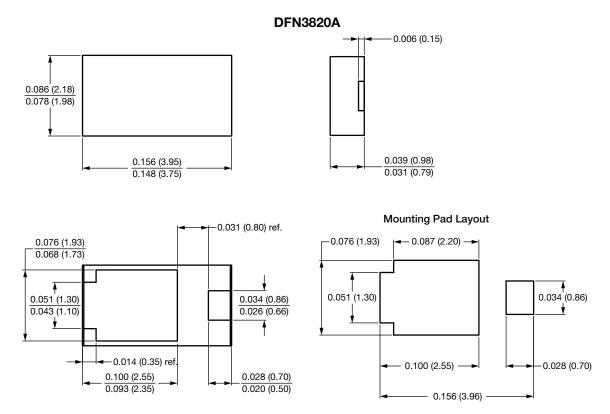
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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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